1753

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PTO IDENTIFIER:

Application Number

10/810,718-Conf. #8917

Patent Number

Inventor:

Panayotis C. Andricacos et al.

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US Patent and Trademark Office

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20140-00255-US3

PAGES (including Cover Sheet):

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Docket No.: 20140-00255-US3

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In re Patent Application of: Panayotis C. Andricacos et al.

Application No.: 10/810,718

Filed: March 29, 2004

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INTERCONNECTION STRUCTURE, PROCESS FOR MAKING AND ELECTROPLATING BATH Art Unit: 1753

Examiner: Not Yet Assigned

Confirmation No.: 8917

INFORMATION DISCLOSURE STATEMENT (IDS)

Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450

Dear Sir:

For:

Pursuant to 37 CFR 1.56, 1.97 and 1.98, the attention of the Patent and Trademark Office is hereby directed to the references listed on the attached PTO/SB/08. It is respectfully requested that the information be expressly considered during the prosecution of this application, and that the references be made of record therein and appear among the "References Cited" on any patent to issue therefrom.

This Information Disclosure Statement is filed before the mailing date of a first Office Action on the merits as far as is known to the undersigned (37 CFR 1.97(b)(3)).

Copies of the references on the PTO/SB/08 are not provided.

Those patent(s) or publication(s) which are marked with a double asterisk (**) next to the Cite No. in the attached form PTO/SB/08 (facsimile) are not supplied because they were previously cited by or submitted to the Office in a prior application number 09/684,786, filed

Application No.: 10/810,718

Docket No.: 20140-00255-US3

October 10, 2000 and relied upon in this application for an earlier filing date under 35 U.S.C. 120.

In accordance with 37 CFR 1.97(g), the filing of this Information Disclosure Statement shall not be construed to mean that a search has been made or that no other material information as defined in 37 CFR 1.56(a) exists. In accordance with 37 CFR 1.97(h), the filing of this Information Disclosure statement shall not be construed to be an admission that any patent, publication or other information referred to therein is "prior art" for this invention unless specifically designated as such.

It is submitted that the Information Disclosure Statement is in compliance with 37 CFR 1.98 and the Examiner is respectfully requested to consider the listed references.

The Director is hereby authorized to charge any deficiency in the fees filed, asserted to be filed or which should have been filed herewith (or with any paper hereafter filed in this application by this firm) to our Deposit Account No. 50-0510, under Order No. 20140-00255-US2.

Dated: 7-16-04

Respectfully submitted,

Burton A. Amernick

Registration No.: 24,852

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				Application Number	10/810,718-Conf. #8917	
INFORMATION DISCLOSURE STATEMENT BY APPLICANT				Filing Date	March 29, 2004	
				First Named Inventor	Panayotis C. Andricacos	
(Use as many sheets as necessary)			FELOAM	Art Unit	1753	
			iecessery)	Examiner Name	Not Yet Assigned	
Sheet		of	1	Attorney Docket Number	20140-0255-US3	

		<u> </u>	U.S. PA	TENT DOCUMENTS	
Examinar initials*	Cite	Document Number Number-Kind Code ² (if known)	Publication Date	Name of Patentee or	Pages, Columns, Linea, Where Relevant Passages or Relevant Figures Appear
	·	US-5,484,518		GOLDBERG	
		US-6,261,433	07/2001	LANDAU	
		US-6,331,237		ANDRICACUS et al.	
 _	AD**	US-6,113,771	09-05-2000	LANDAU et al.	

FOREIGN PATENT DOCUMENTS						4
Exeminor Intides	Cite No.1	Foreign Patent Document Country Code ³ -Number ⁴ -Kind Code ⁴ (# Imourn)	Publication Date	Name of Patentee or	Pages, Columns, Lines, Where Relevant Passages or Relevant Figures Appear	۳
	·			LANDAU, et al.		

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		NON PATENT LITERATURE DOCUMENTS	
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	CATT	A Novel Electrolyte Composition for Copper Plating in Wafer Metallization; Electrochemical Processing in ULSI Fabrication and Semiconductor/Metal Deposition II: Proceedings of the Intenational Symposium; P.C.: Uziel LANDAU, et al., The Electrochemical Society, Inc.	
	CB**	A Model of Superfilling in Damascene Electroplating; H. DELIGIANNI, 8(81.; The 195 Intenting Abstracts, Volume 99-1 (May 2-6, 1999).	L
	CC-	Model of Wafer Thickness Uniformity in an Electroplating 1991, The 1991 Wiceting of	
· ·	CD**	A Model of Superfilling in Damascene Electroplating: H. DELIGIANN, et al., Electroplating: Processing in ULSI Fabrication and Semiconductor/Metal Deposition II: Proceedings of the International Symposium; P.C.: Uziel LANDAU, et al., The Electrochemical Society, Inc.,	
	CE"	Proceedings Volume 99-9. Uziel LANDAU, A Novel Electrolyte Composition for Copper Plating in Wafer Metallization, Abstract No. 263.	
	CF**	Model of Wafer Thickness Uniformity in an Electrocoplating Tool, Electrochemical Fricessing in ULSI Fabrication and Semicondutor/Metal Deposition II: Proceedings of the International Symposium; P.C.H. DELIGIANNI, et al., The Electrochemical Society, Inc., Proceedings	
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